

GT50100B IST COUPON INFORMATION (Through Hole)
(With capacitance holes)

This package contains design files for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole** Technology on a 6.0" (152.4 mm) X 0.85" (21.5 mm) coupon with a total thickness up to but not exceeding .125" (3.2mm) and limited to a minimum of 6 layers. This coupon is designed on two independent grid sizes, .050" (1.27mm) and .100" (2.54mm). The maximum hole/pad size for the .050" (1.27mm) grid is .018" (.46mm) / .032" (.81mm) for both power 1 and sense 1 circuit. The maximum hole/pad size for the .100" (2.54mm) grid is .056" (1.42mm) and pad size is .068" (1.73mm) for power 2 circuit and .018" (.46mm) / .032" (.81mm) for sense 2 circuit; Decreasing these feature sizes will not affect the coupon functionality but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

